

REMARKS/ARGUMENTS**1. Request for Continued Examination:**

5 The applicant respectfully requests continued examination of the above-indicated application as per 37 CFR 1.114.

The amendments made to the claims in the above section are over the last entered amendment filed December 21, 2005.

10 2. Rejection of claims 11, 19, and 33-34 under 35 U.S.C. 102(e):

Claims 11, 19, and 33-34 are rejected under 35 U.S.C. 102(e) as being anticipated by Hatauchi (US 6,858,920).

Response:

15 The applicant would like to explain the patentable features of claims 11, 19, 33, and 34 with respect to Hatauchi.

20 In the present invention, a bonding pad is corresponding to at least two bonding options: a corresponding first lead frame and the package substrate. With such arrangement, the bonding pad is connected to one of the corresponding first lead frame and the package substrate to construct one option, leaving the other option unconnected.

25 The applicant wishes to provide the following two figures for illustration purposes only. Figure A below is based on figure 6 of the instant application as filed.

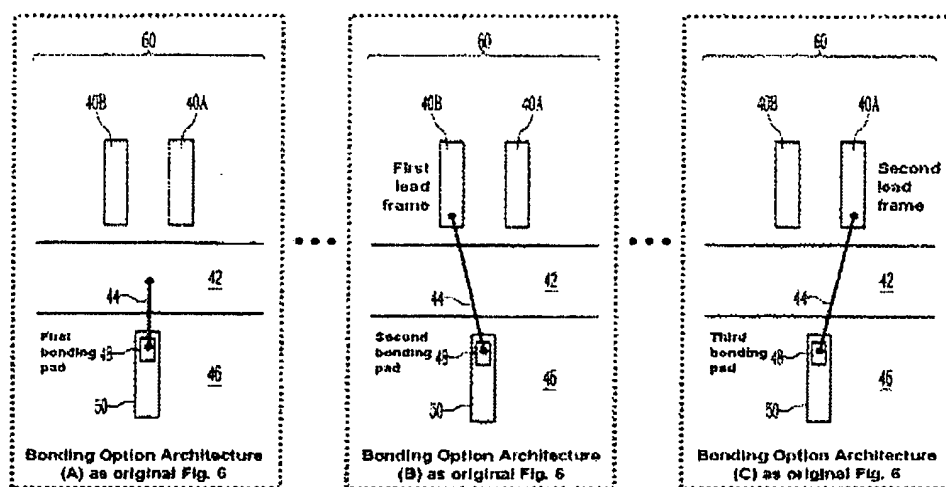


Figure A

As shown in Figure A, three bonding options, lead frames 40A, 40B and the package substrate, are available to form three different options. As shown in Figure B below, a bonding pad 26 can connect to one of two corresponding lead frames 20 or to the package substrate 22.

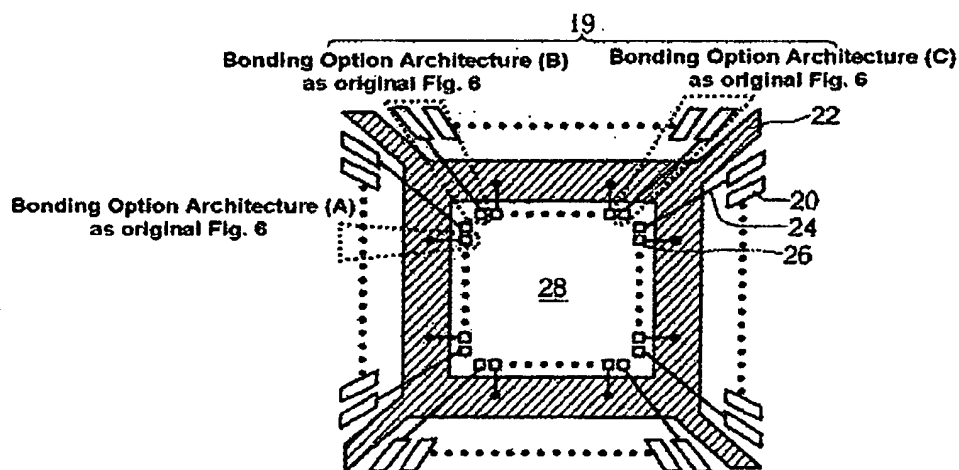


Figure B

In the application as filed, figure 6 and paragraphs 0021-0023 show support for a

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bonding pad having three bonding options. In paragraph 0021, lines 2-6 show support for a first lead frame 40A, a second lead frame 40B, and a package substrate 42. In paragraph 0022, lines 6-11 show that there are three possible bonding options for a bonding pad 48, which are the first lead frame 40A, the second lead frame 40B, and the package substrate 42.

In paragraph 0025 of the specification, the following advantages are mentioned, "...the present invention has the following advantages: 1. Provide convenient testing and other functions for a chip, and let a single chip operate in different modes." As shown in Figure A above, bonding option architectures (A) and (B) shows two modes. While designing a chip (such as chip 28), different functions can be implemented in a single chip, and a pad 48 can be used to select which function is enabled. For example, if pad 48 is connected to HIGH, chip 28 enables function A; if pad 48 is connected to LOW, chip 28 enables function B instead of function A. In this way, we can realize two different kinds of IC's using one chip design to lower our IC cost. This is the meaning of the phrase "let a single chip operate in different modes" that is written in paragraph 0025 of original specification. In the bonding option architecture (C) of Figure A, pad 48 is connected to another lead frame 40A. This is a test mode. If the IC vendor knows that this lead frame 40A is reserved, this lead frame can be alternatively held either high or low for testing the various functions (like function A and B). This is how the present invention is able to "provide convenient testing...mode", as explained in paragraph 0025 of the original specification.

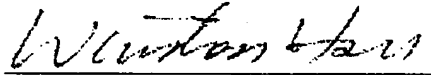
Hatauchi, on the other hand, does not teach that a bonding pad has a corresponding first lead frame or a corresponding second lead frame. As shown in Fig.2 of Hatauchi, each bonding pad 4a only has a corresponding first lead frame 5 (the horizontal lead frames), but no corresponding second lead frame. Similarly, each bonding pad 4d only has a corresponding second lead frame 5 (the vertical lead frames), but no corresponding first lead frame. Furthermore, bonding pads 4b and 4c do not have corresponding first or second lead frames. Therefore, Hatauchi does not provide a bonding pad with multiple bonding options, as is the case with the claimed invention according to claims 11, 19, 33, and 34.

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Since Hatauchi does not teach that a bonding pad has a corresponding first lead frame, and also does not teach that a bonding pad has a corresponding second lead frame, Hatauchi fails to teach all of the claimed limitations of claims 11, 19, 33, and 34. For these reasons, reconsideration of claims 11, 19, 33, and 34 is respectfully requested.

Applicant respectfully requests that a timely Notice of Allowance be issued in this case.

Sincerely yours,



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Note: Please leave a message in my voice mail if you need to talk to me. (The time in D.C. is 12 hours behind the Taiwan time, i.e. 9 AM in D.C. = 9 PM in Taiwan.)